

CMPA5585030F

30 W, 5.5 - 8.5 GHz, GaN MMIC, Power Amplifier

Description

WolfSpeed's CMPA5585030F is a gallium nitride (GaN) High Electron Mobility Transistor (HEMT) based monolithic microwave integrated circuit (MMIC). GaN has superior properties compared to silicon or gallium arsenide, including higher breakdown voltage, higher saturated electron drift velocity and higher thermal conductivity. GaN HEMTs also offer greater power density and wider bandwidths compared to Si and GaAs transistors. This MMIC is available in a 10 lead metal/ceramic flanged package for optimal electrical and thermal performance.



Package Type: 440213
PN: CMPA5585030F

Typical Performance Over 5.8 - 8.4 GHz ($T_c = 25^\circ\text{C}$)

Parameter	5.8 GHz	6.4 GHz	7.2 GHz	7.9 GHz	8.4 GHz	Units
$S_{21}^{1,2}$	25.9	23.8	26.5	24.5	26.7	dB
Power Gain ^{2,5}	22.3	19.0	20.9	21.6	21.2	
PAE ^{1,2,4,5}	24.7	20.7	20.3	22.6	22.9	%
ACLR ^{1,2,3,5}	-37	-42	-33	-34	-40	dBc

Notes (unless otherwise specified):

¹ At 25°C

² Measurements are performed using WolfSpeed test fixture AD-938516

³ Under OQPSK modulated signal, 1.6 Msps, PN23, Alpha Filter = 0.2

⁴ Power Added Efficiency = $(P_{OUT} - P_{IN}) / PDC$

⁵ Measured at $P_{OUT} = 41 \text{ dBm}$

Features

- 25 dB Small Signal Gain
- 30 W Typical P_{SAT}
- Operation up to 28 V
- High Breakdown Voltage
- High Temperature Operation
- Size 1.00 x 0.385 inches

Applications

- Point to Point Radio
- Communications Radar
- Satellite Communication Uplink





Absolute Maximum Ratings (not simultaneous)

Parameter	Symbol	Rating	Units	Conditions
Drain-source Voltage	V_{DSS}	150	V_{DC}	25°C
Gate-source Voltage	V_{GS}	-10, +2		
Storage Temperature	T_{STG}	-65, +150	°C	
Operating Junction Temperature	T_J	225		
Maximum Forward Gate Current	I_{GMAX}	10	mA	25°C
Soldering Temperature ¹	T_S	245	°C	
Screw Torque	τ	40	in-oz	
CGHV40180F Thermal Resistance, Junction to Case	$R_{\theta JC}$	2.16	°C/W	CW, 85°C, $P_{DISS} = 66\text{ W}$
Case Operating Temperature	T_C	-40, +150	°C	

Note:

¹ Refer to the Application Note on soldering at wolfspeed.com/rf/document-library

Electrical Characteristics (Frequency = 5.5 GHz to 8.5 GHz unless otherwise stated; $T_C = 25^\circ\text{C}$)

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
DC Characteristics¹						
Gate Threshold Voltage	$V_{GS(th)}$	-3.8	-2.8	-2.3	V	$V_{DS} = 10\text{ V}$, $I_{DS} = 12.7\text{ mA}$
Saturated Drain Current ²	I_{DS}	9.2	12.7	—	A	$V_{DS} = 6.0\text{ V}$, $V_{GS} = 2.0\text{ V}$
Drain-Source Breakdown Voltage	V_{BD}	84	—	—	V	$V_{GS} = -8\text{ V}$, $I_{DS} = 12.7\text{ mA}$
RF Characteristics³						
Small Signal Gain	S21	22.85	26	—	dB	$V_{DD} = 28\text{ V}$, $I_{DQ} = 285\text{ mA}$, $P_{IN} = -20\text{ dBm}$
Input Return Loss	S11	—	-7	—		
Output Return Loss	S22	—		—		
Output Mismatch Stress	VSWR	—	—	5:1	Ψ	No damage at all phase angles, $V_{DD} = 28\text{ V}$, $I_{DQ} = 285\text{ mA}$, $P_{OUT} = 43\text{ dBm}$

Notes:

¹ Measured on-wafer prior to packaging

² Scaled from PCM data

³ Measured using network analyzer (Power = -20 dBm)



Electrical Characteristics Continued ($T_c = 25^\circ\text{C}$)

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
RF Characteristics^{1,2,4,6}						
Power Added Efficiency at 5.8 GHz ⁵	PAE ₁	19.0	25.8	—	%	V _{DD} = 28 V, I _{DQ} = 285 mA, P _{IN} = 41 dBm
Power Added Efficiency at 6.4 GHz ⁵	PAE ₂	16.0	22.4	—		
Power Added Efficiency at 7.2 GHz ⁵	PAE ₃	16.2	22.0	—		
Power Added Efficiency at 7.9 GHz ⁵	PAE ₄	18.0	23.9	—		
Power Added Efficiency at 8.4 GHz ⁵	PAE ₅	19.2	25.0	—		
Power Gain at 5.8 GHz	G _{P1}	18.25	22.4	—	dB	
Power Gain at 6.4 GHz	G _{P2}	16.35	20.2	—		
Power Gain at 7.2 GHz	G _{P3}	16.85	21.0	—		
Power Gain at 7.9 GHz	G _{P4}	17.15	22.2	—		
Power Gain at 8.4 GHz	G _{P5}	17.65	21.8	—		
OQPSK Linearity at 5.8 GHz	ACLR ₁	—	-42	-32	dBc	
OQPSK Linearity at 6.4 GHz	ACLR ₂	—	-44	-33		
OQPSK Linearity at 7.2 GHz	ACLR ₃	—	-34	-27.5		
OQPSK Linearity at 7.9 GHz	ACLR ₄	—	-37	-28		
OQPSK Linearity at 8.4 GHz	ACLR ₅	—	-40	-32		

Notes:

1 At 25°C

2 Measurements are to be performed using Wolfspeed CMPA5585030F-AMP

3 Measured using network analyzer (Power = -20 dBm)

4 Under OQPSK modulated signal, 1.6 Msps, PN23, Alpha Filter = 0.2

5 Power Added Efficiency = (P_{OUT} - P_{IN})/PDC

6 Fixture loss de-embedded using the following offset. The offset is subtracted from the input offset value and added to the output offset value.

a. 5.8 GHz - 0.182 dB

b. 6.4 GHz - 0.200 dB

c. 7.2 GHz - 0.217 dB

d. 7.9 GHz - 0.234 dB

e. 8.4 GHz - 0.246 dB

Electrostatic Discharge (ESD) Classifications

Parameter	Symbol	Class	Classification Level	Test Methodology
Human Body Model	HBM	2	ANSI/ESDA/JEDEC JS-001 Table 3	JEDEC JESD22 A114-D
Charge Device Model	CDM	C3	ANSI/ESDA/JEDEC JS-002 Table 3	JEDEC JESD22 C101-C



Typical Performance of the CPM5585030F

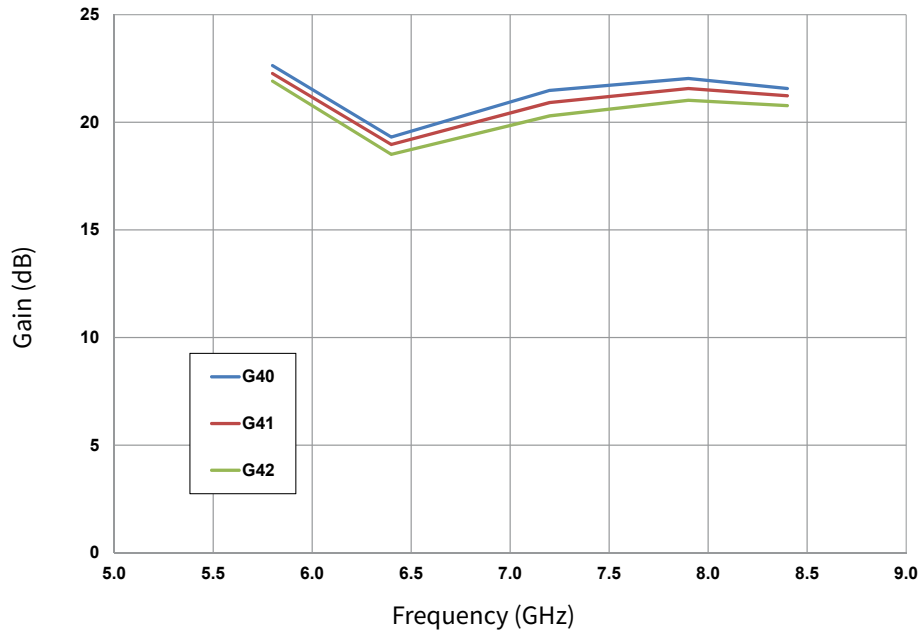


Figure 1. Gain vs. Frequency & Output Power OQPSK 1.6 Msps
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 285\text{ mA}$

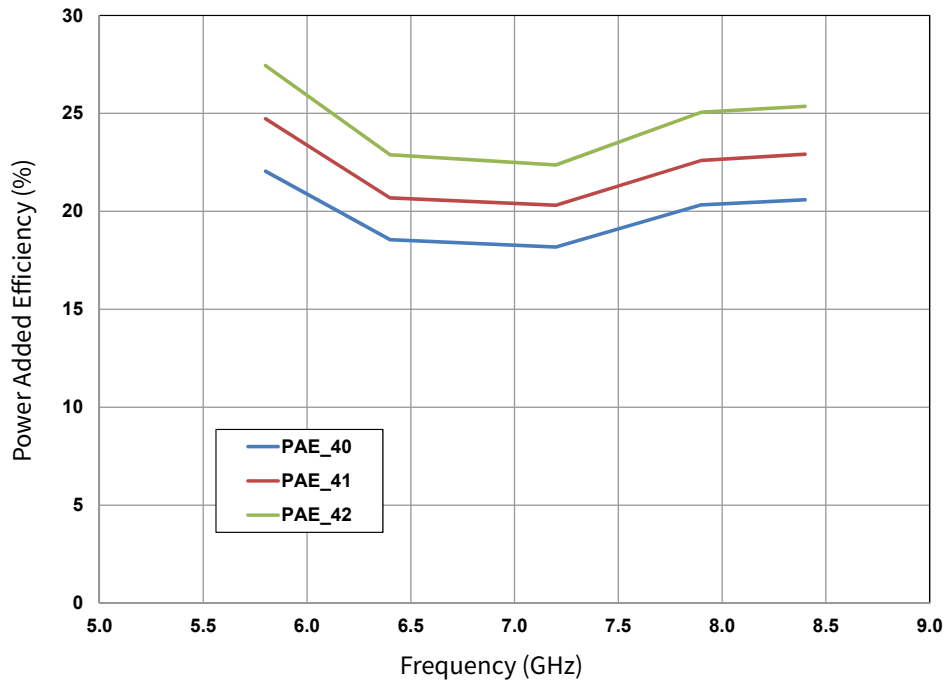


Figure 2. Power Added Efficiency vs. Frequency & Output Power OQPSK
 1.6 Msps $V_{DD} = 28\text{ V}$, $I_{DQ} = 285\text{ mA}$



Typical Performance of the CPM5585030F

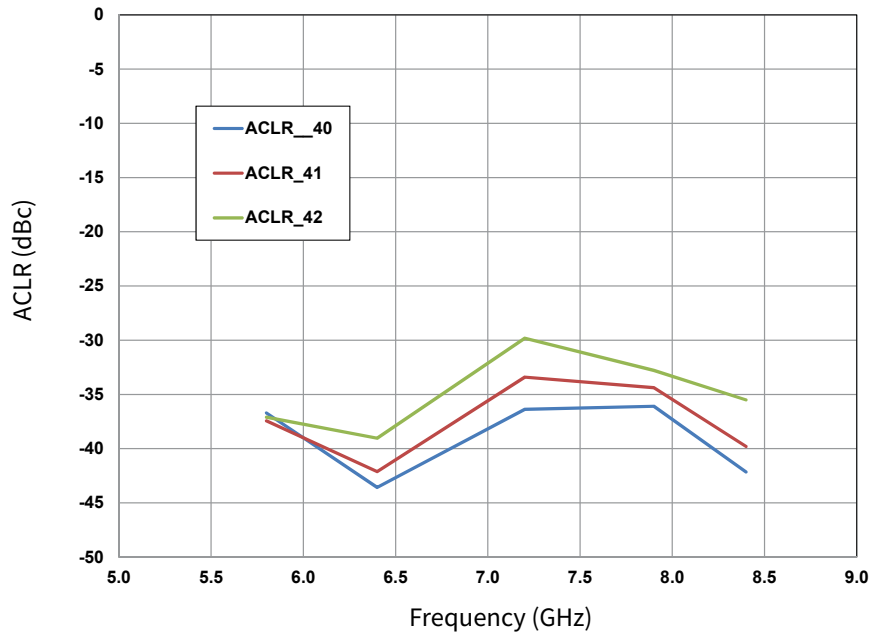


Figure 3. ACLR vs. Frequency & Output Power OQPSK 1.6 Msps
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 285\text{ mA}$

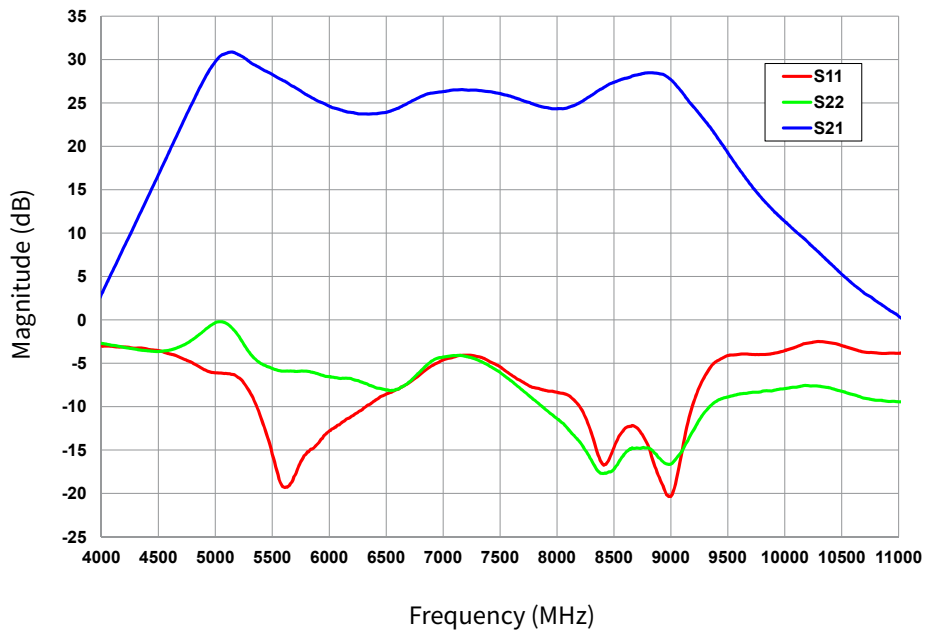


Figure 4. Typical S-Parameters
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 285\text{ mA}$



Typical Performance of the CPM5585030F

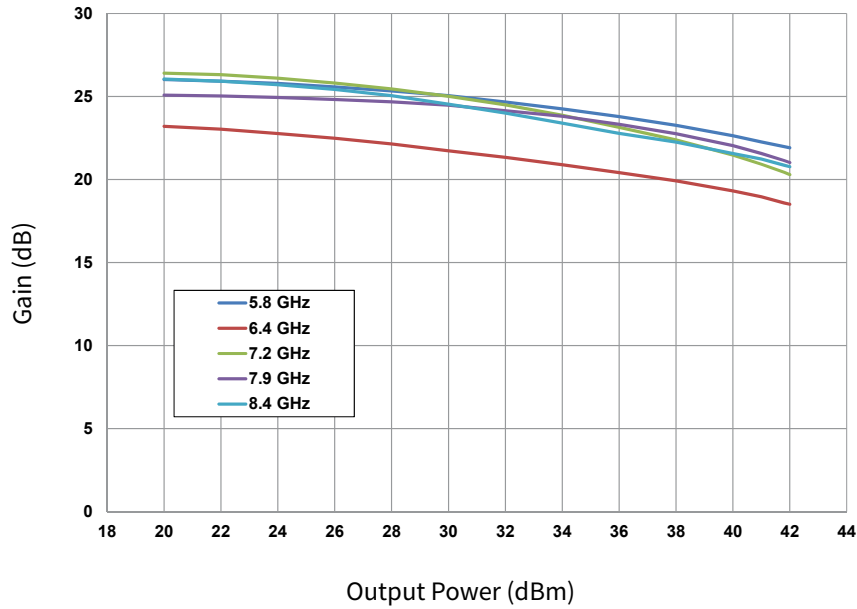


Figure 5. Gain vs. Output Power and Frequency OQPSK 1.6 Msps
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 285\text{ mA}$

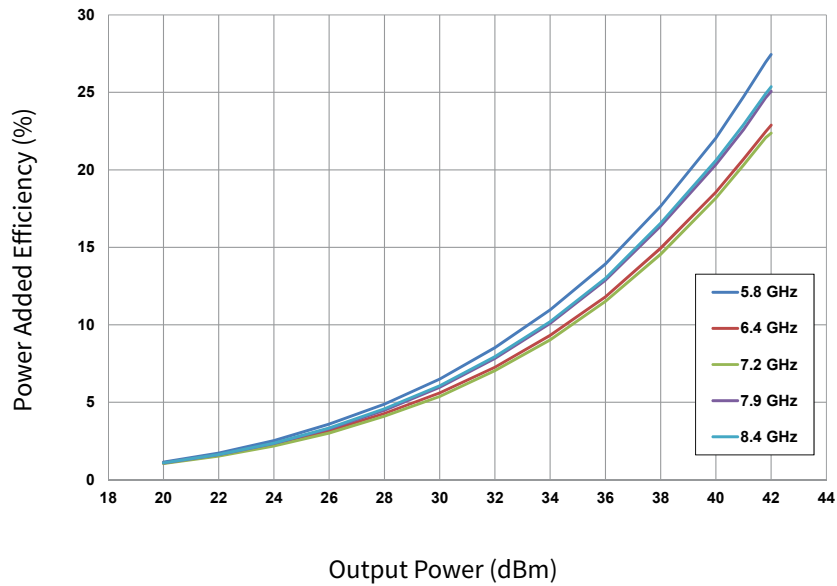


Figure 6. Power Added Efficiency vs. Output Power and Frequency OQPSK
 1.6 Msps $V_{DD} = 28\text{ V}$, $I_{DQ} = 285\text{ mA}$



Typical Performance of the CPM5585030F

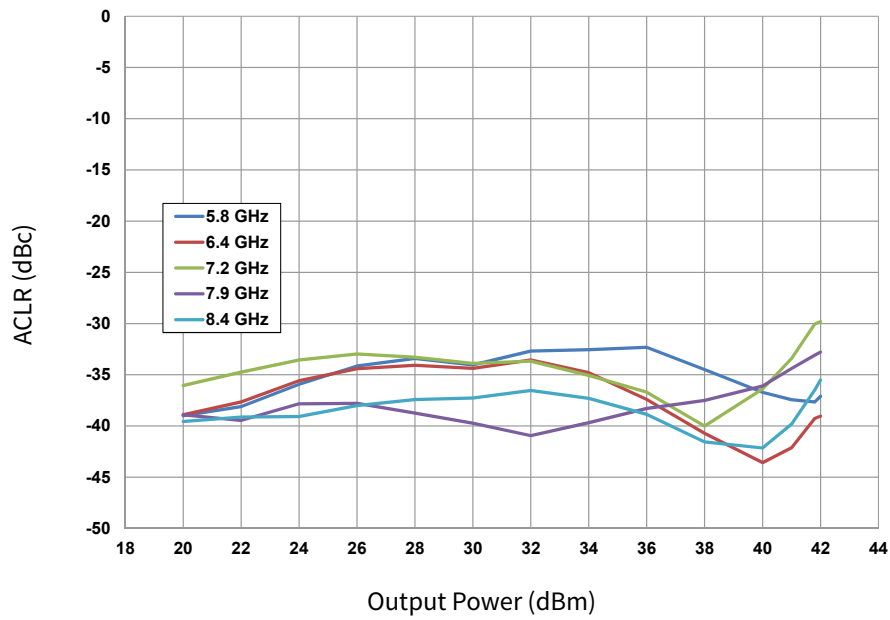


Figure 7. ACLR vs. Output Power and Frequency QPSK 1.6 Msps
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 285\text{ mA}$

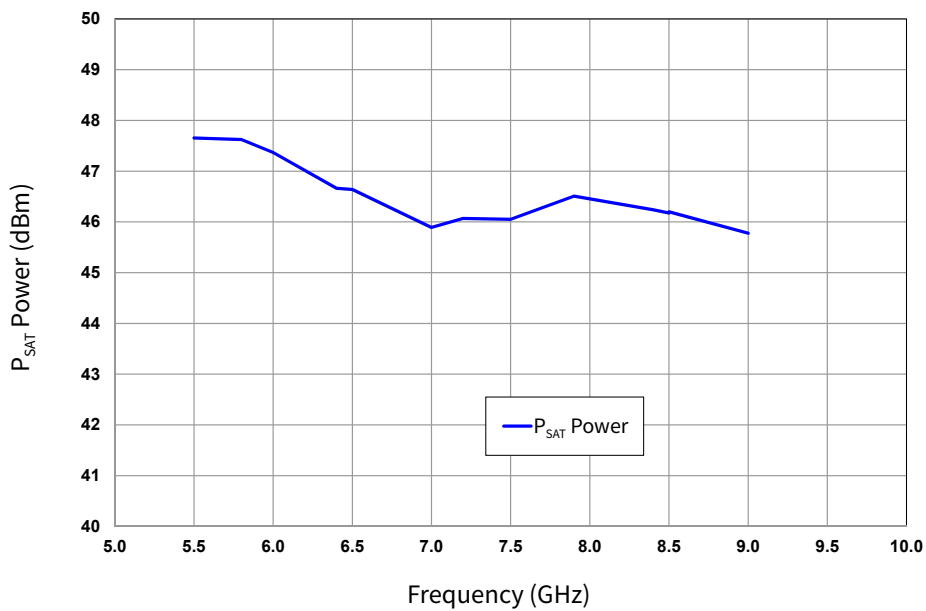


Figure 8. P_{SAT} Power vs. Frequency
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 800\text{ mA}$, Pulsed Width = 100μs, Duty Cycle = 10%



Typical Performance of the CPMA5585030F

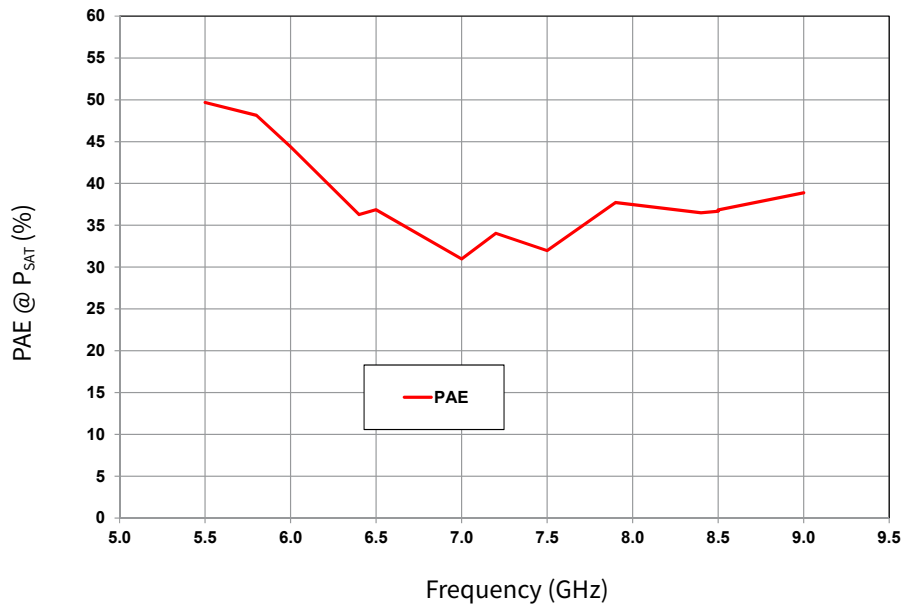


Figure 9. Power Added Efficiency @ Saturated Power vs. Frequency
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 800\text{ mA}$, Pulsed Width = $100\mu\text{s}$, Duty Cycle = 10%

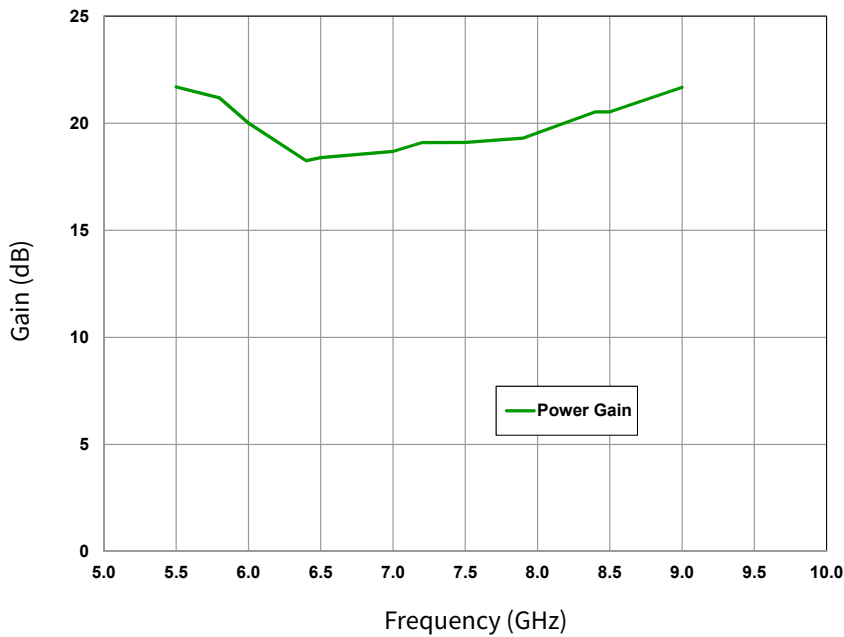


Figure 10. Gain @ Saturated Power vs. Frequency
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 800\text{ mA}$, Pulsed Width = $100\mu\text{s}$, Duty Cycle = 10%



Typical Performance of the CPM5585030F

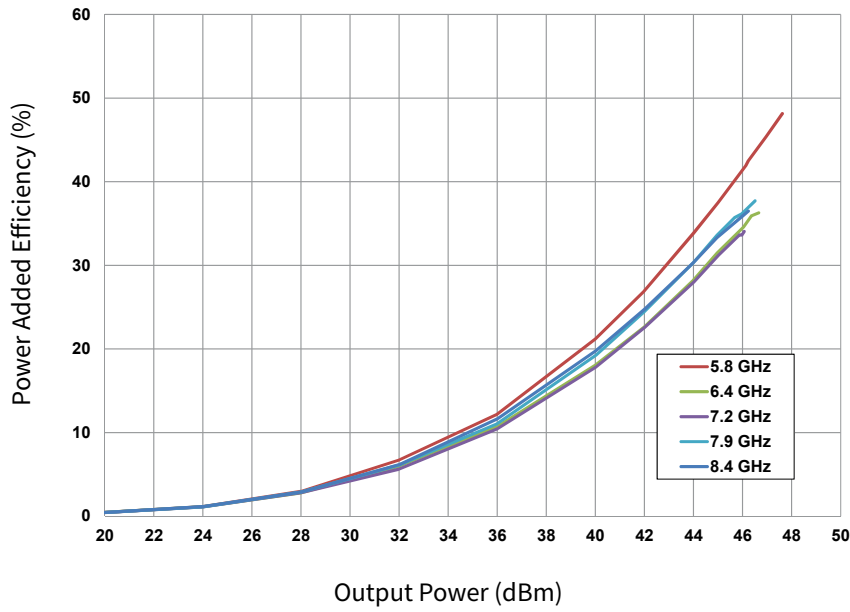


Figure 11. PAE vs. Output Power and Frequency
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 800\text{ mA}$, Pulsed Width = 100 μs , Duty Cycle = 10%

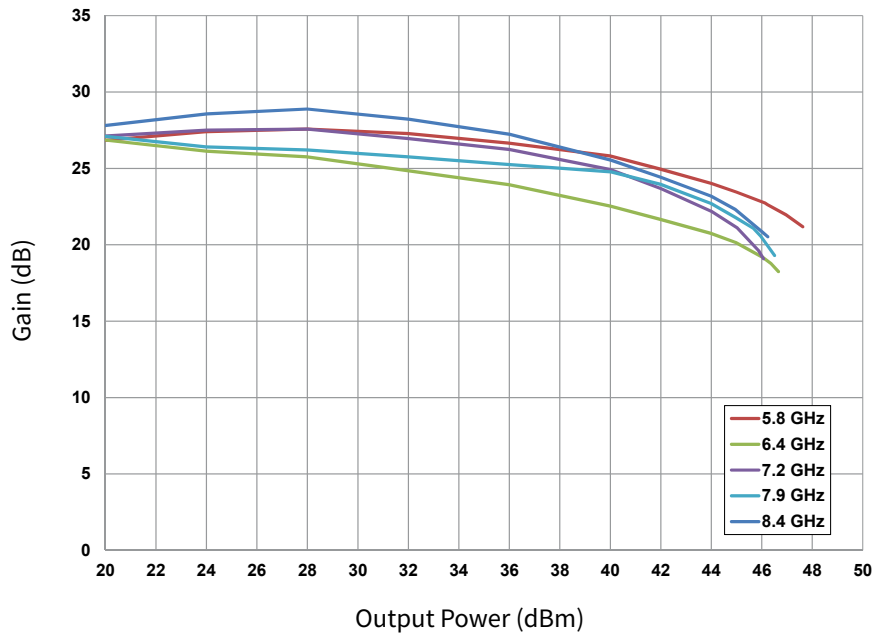
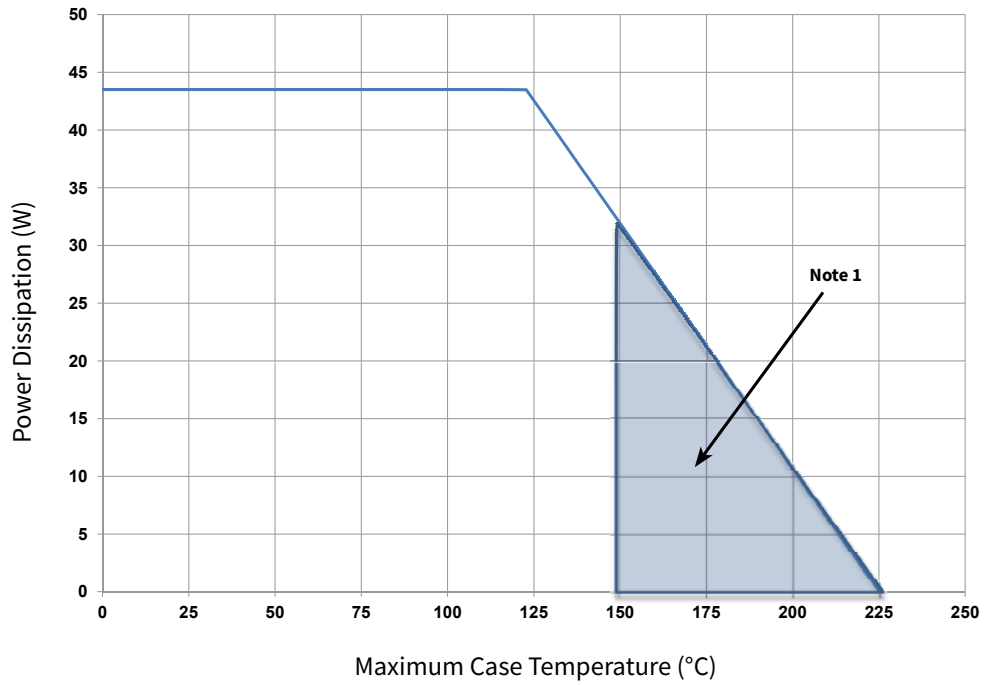


Figure 12. Gain vs. Output Power and Frequency
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 800\text{ mA}$, Pulsed Width = 100 μs , Duty Cycle = 10%



CMPA5585030F Power Dissipation De-rating Curve



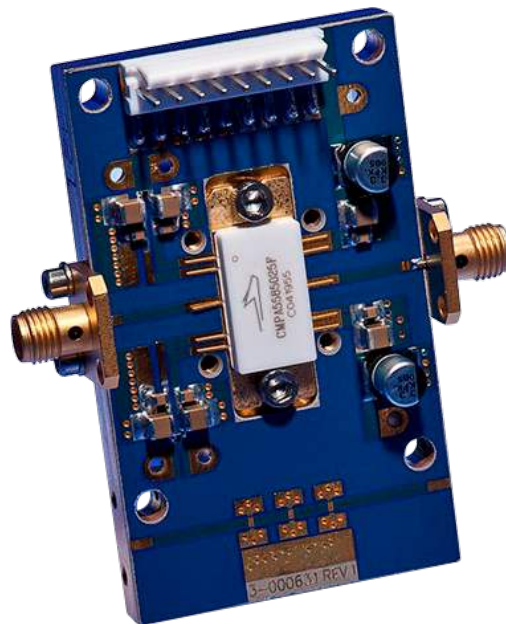
Note:
1 Area exceeds Maximum Case Operating Temperature (See Page 2)



CMPA5585030F-AMP Application Circuit Bill of Materials

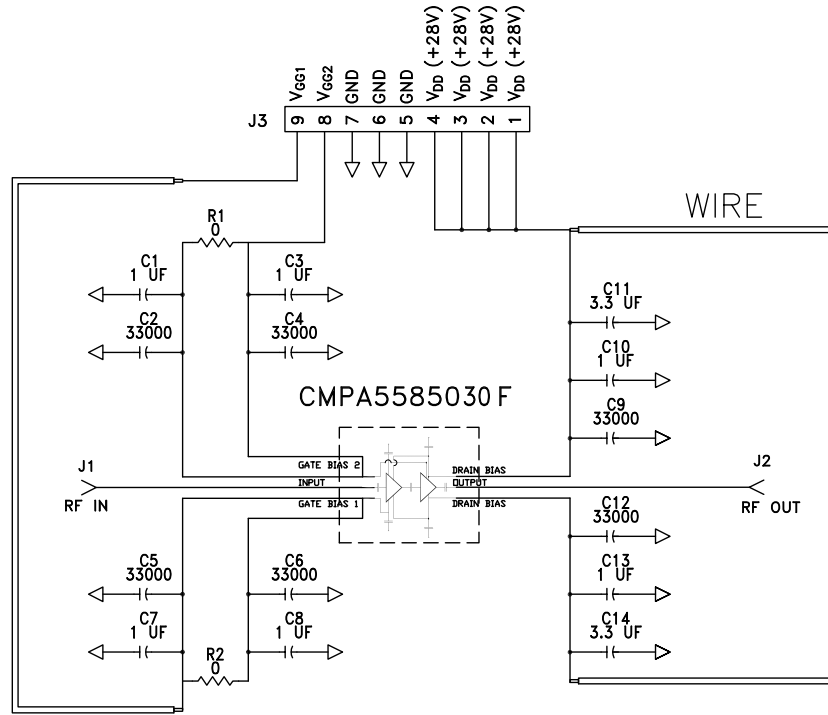
Designator	Description	Qty
C1, C3, C7, C8, C10, C13	CAP, 1.0μF, +/-10%, 1210, 100V, X7R	6
C2, C4, C5, C6, C9, C12	CAP, 33000pF, 0805, 100V, X7R	6
C11, C14	CAP ELECT 3.3μF 80V FK SMD	2
R1, R2	RES 0.0 OHM 1/16W 0402 SMD	2
J1, J2	CONN, SMA, PANEL MOUNT JACK, FLANGE, 4-HOLE, BLUNT POST, 20MIL	2
J3	CONNECTOR, HEADER, RT>PLZ .1CEN LK 9POS	1
	PCB, TACONIC, RF-35P-0200-CL1/CL1	1
Q1	CMPA5585030F	1

CMPA5585030F-AMP Demonstration Amplifier Circuit

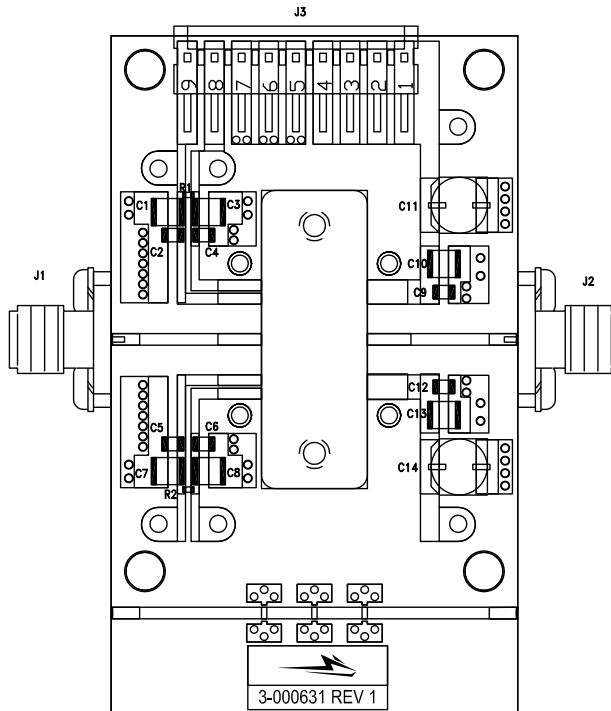




CMPA5585030F-AMP Demonstration Amplifier Circuit



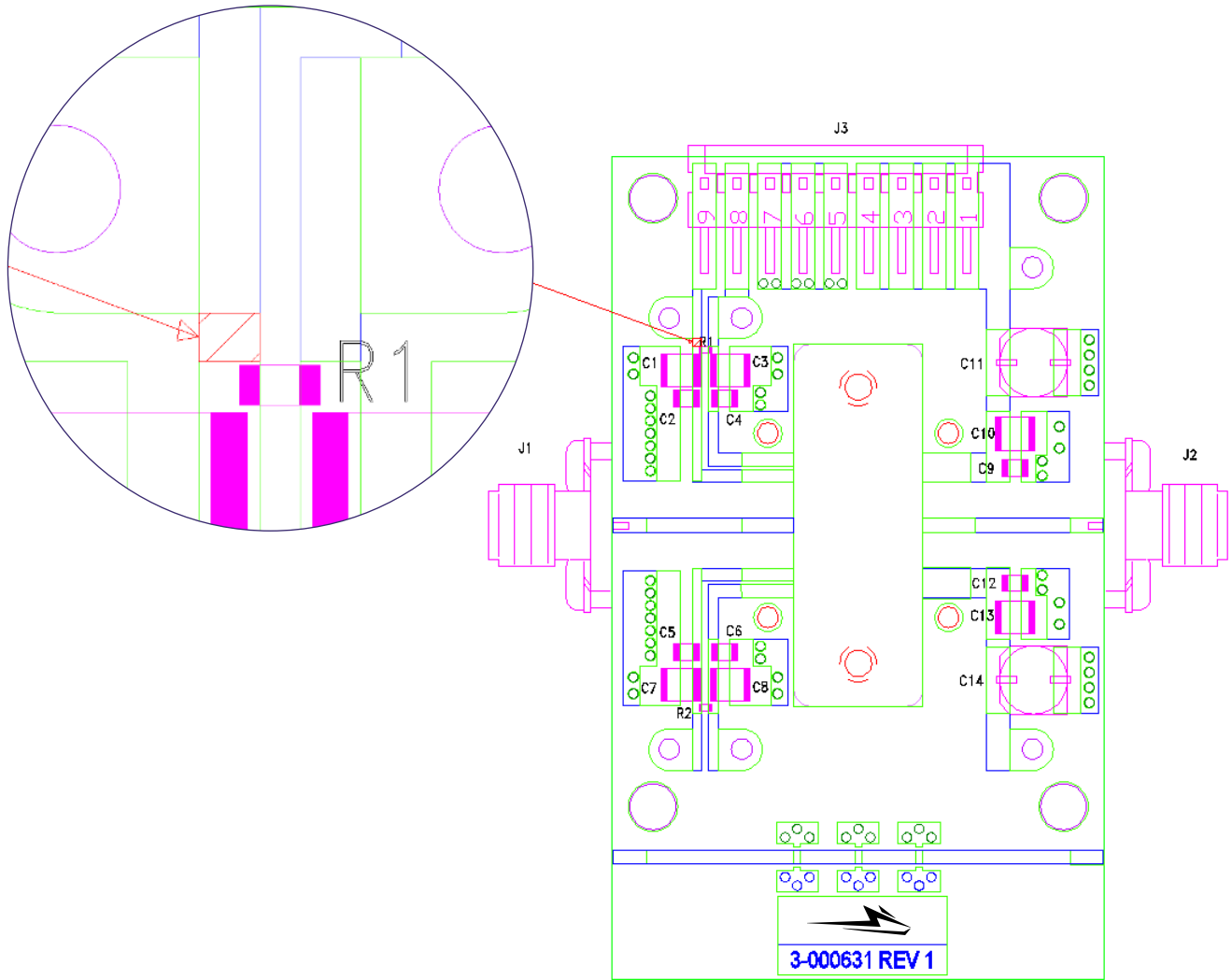
CMPA5585030F-AMP Demonstration Amplifier Circuit Outline





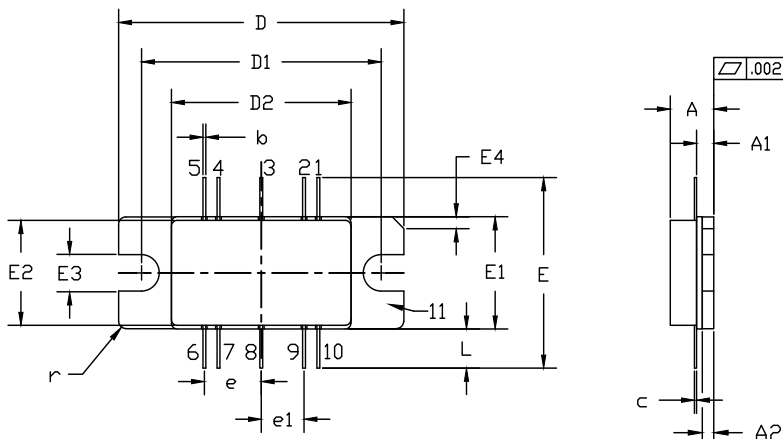
CMPA5585030F-AMP Demonstration Amplifier Circuit

To configure the CMPA5585030F test fixture to enable independent VG1 / VG2 control of the device, a cut must be made to the microstrip line just above the R1 resistor as shown. Pin 9 will then supply VG1 and Pin 8 will supply VG2.





Product Dimensions CMPA5585030F (Package Type – 440213)



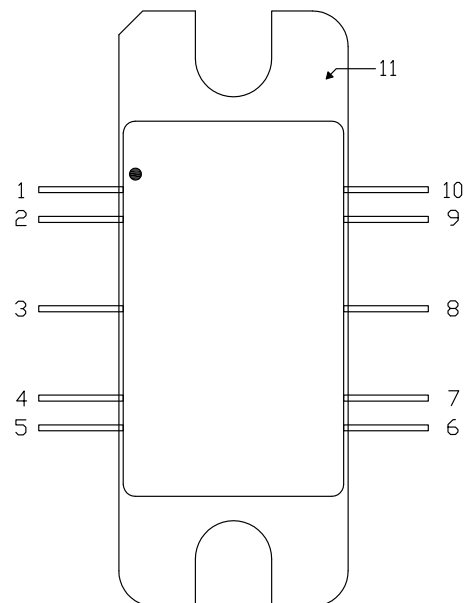
PIN 1: GATE BIAS 6: DRAIN BIAS
 2: GATE BIAS 7: DRAIN BIAS
 3: RF IN 8: RF OUT
 4: GATE BIAS 9: DRAIN BIAS
 5: GATE BIAS 10: DRAIN BIAS
 11: SOURCE

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M - 1994.
2. CONTROLLING DIMENSION: INCH.
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
4. LID MAY BE MISALIGNED TO THE BODY OF PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.

DIM	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.148	0.168	3.76	4.27	
A1	0.055	0.065	1.40	1.65	
A2	0.035	0.045	0.89	1.14	
b	0.01 TYP		0.254 TYP		10x
c	0.007	0.009	0.18	0.23	
D	0.995	1.005	25.27	25.53	
D1	0.835	0.845	21.21	21.46	
D2	0.623	0.637	15.82	16.18	
E	0.653 TYP		16.59 TYP		
E1	0.380	0.390	9.65	9.91	
E2	0.355	0.365	9.02	9.27	
E3	0.120	0.130	3.05	3.30	
E4	0.035	0.045	0.89	1.14	45° CHAMFER
e	0.200 TYP		5.08 TYP		4x
e1	0.150 TYP		3.81 TYP		4x
L	0.115	0.155	2.92	3.94	10x
r	0.025 TYP		.635 TYP		3x

PIN	Qty
1	Gate Bias for Stage 2
2	Gate Bias for Stage 2
3	RF In
4	Gate Bias for Stage 1
5	Gate Bias for Stage 1
6	Drain Bias
7	Drain Bias
8	RF Out
9	Drain Bias
10	Drain Bias
11	Source





Part Number System

CMPA5585030F

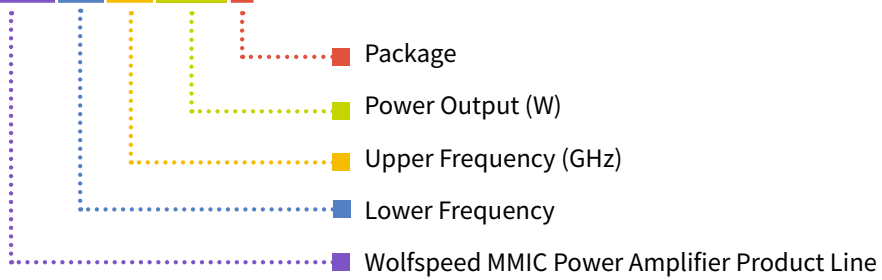


Table 1.

Parameter	Value	Units
Lower Frequency	5.5	GHz
Upper Frequency ¹	8.5	
Power Output	30	W
Package	Flange	–

Note:



¹ Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.

Table 2.

Character Code	Code Value
A	0
B	1
C	2
D	3
E	4
F	5
G	6
H	7
J	8
K	9
Examples	1A = 10.0 GHz 2H = 27.0 GHz



Product Ordering Information

Order Number	Description	Unit of Measure	Image
CPMA5585030F	GaN MMIC	Each	
CPMA5585030F-AMP	Test board with GaN MMIC installed	Each	

**For more information, please contact:**

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